AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

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Claim 1 (currently amended): A quantum semiconductor device comprising:

a first semiconductor layer formed [[on]] <u>over</u> a substrate and having a two-dimensional carrier gas formed in;

a quantum dot formed [[on]] over the first semiconductor layer;

a second semiconductor layer formed [[on]] over the first semiconductor layer, covering

burying the quantum dot;

a dot-shaped structure formed on the surface of the second semiconductor layer at a position

above the quantum dot; and

[[an]] oxide layer layers formed on [[two]] both sides of the dot-shaped structure on the upper

surface of the second semiconductor layer.

Claim 2 (original): A quantum semiconductor device according to claim 1, wherein

the dot-shaped structure is caused to form on the surface of the second semiconductor layer

at a position above the quantum dot due to crystal strains generated in the surface of the second

semiconductor layer due to the presence of the quantum dot.

Claim 3 (original): A quantum semiconductor device according to claim 1, wherein the quantum dot is in a three-dimensionally grown island self-assembled by S-K mode. 2 Claim 4 (original): A quantum semiconductor device according to claim 1, wherein 1 the dot-shaped structure is in a three-dimensionally grown island self-assembled by S-K mode. 3 Claim 5 (original): A quantum semiconductor device according to claim 1, wherein 1 a depletion region is formed due to the presence of the oxide layer in a region of the first semiconductor layer, which is below the oxide layer, and a channel region is defined by the depletion region. 4 Claim 6 (original): A quantum semiconductor device according to claim 5, further 1 comprising: source/drain regions connected to both ends of the channel region. 3 Claim 7 (original): A quantum semiconductor device according to claim 1, further 1 comprising: 2 a gate electrode connected to the dot-shaped structure. 3

Claim 8 (original): A quantum semiconductor device according to claim 1, wherein a distance between the two-dimensional carrier gas and the quantum dot is 5 nm or less. 2 Claim 9 (original): A quantum semiconductor device according to claim 1, wherein 1 the dot-shaped structure is in another quantum dot or an anti-dot. 2 Claim 10 (original): A quantum semiconductor device according to claim 1, wherein 1 at least a part of the dot-shaped structure is oxidized. 2 Claim 11 (currently amended): A method for fabricating a quantum semiconductor device comprising the steps of: 2 forming [[on]] over a substrate a first semiconductor layer with a two-dimensional carrier gas 3 formed in; forming a quantum dot [[on]] over the first semiconductor layer; 5 forming a second semiconductor layer, covering burying the quantum dot; 6 forming a dot-shaped structure on the surface of the second semiconductor at a position 7 above the quantum dot due to strains generated in the surface of the second semiconductor layer due 8 to the presence of the quantum dot; and 9 forming [[an]] oxide layer layers on the upper surface of the second semiconductor layer on 10 both side of the dot-shaped structure with the dot-shaped structure as a mark. 11

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Claim 12 (withdrawn): A method for fabricating a quantum semiconductor device according 1 to claim 11, further comprising, after the step of forming the oxide layer, the step of forming source/drain regions with the oxide layer as a mark. 3 Claim 13 (withdrawn): A method for fabricating a quantum semiconductor device according ł to claim 11, wherein 2 in the step of forming the quantum dot, the quantum dot in a three-dimensional grown island 3 is self-assembled by S-K mode. Claim 14 (withdrawn): A method for fabricating a quantum semiconductor device according 1 to claim 11, wherein 2 in the step of forming the dot-shaped structure, the dot-shaped structure in a 3 three-dimensional grown island is self-assembled by S-K mode. 4 Claim 15 (withdrawn): A method for fabricating a quantum semiconductor device according 1 to claim 11, wherein in the step of forming an oxide layer, the oxide layer is formed by bringing a needle-shaped 3 conductor close to the surface of the second semiconductor layer and applying a voltage between the 4 needle-shaped conductor and the substrate.

Claim 16 (withdrawn): A method for fabricating a quantum semiconductor device according

to claim 15, wherein

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the needle-shaped conductor is a probe of an atomic force microscope.